

## **REMARKS**

Claims 1-16 are now pending in the application. The Examiner is respectfully requested to reconsider and withdraw the rejections in view of the amendments and remarks contained herein.

### **REJECTION UNDER 35 U.S.C. § 103**

Claims 1-16 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Hashimoto (U.S. Patent No. 6,475,896 B1) in view of Black et al. (U.S. Patent No. 6,737,364 B2). This rejection is respectfully traversed.

Independent claims 1, 7, 14, and 15 call for forming a wiring layer consisting of wiring extending over the stress relief layer and forming outer electrodes over predetermined portions of the wiring layer to electrically connect the outer electrodes to the wiring layer over the stress relief layer.

In contrast, Hashimoto fails to teach or suggest forming a wiring layer consisting of wiring extending over the stress relief layer and forming outer electrodes over predetermined portions of the wiring layer to electrically connect the outer electrodes to the wiring layer over the stress relief layer. Black also fails to teach this subject matter.

Claim 1 also calls for forming a dielectric layer by applying dielectric liquid by an inkjet method on the predetermined portions after the step of forming the wiring layer such that the dielectric layer and the outer electrodes form capacitors above the stress relief layer. Hashimoto and Black fail to teach or suggest this subject matter.

Claim 7 also calls for forming an inductor on the stress relief layer, which is electrically connected to the wiring layer, by applying conductive liquid in a spiral pattern

by an inkjet method, after the step of forming the wiring layer. Hashimoto and Black fail to teach or suggest this subject matter.

Claim 14 also calls for forming multiple wiring layers in which stress relief layers and wiring layers are alternately laminated and adjacent wiring layers are electrically connected to each other. The step of forming the multiple wiring layers includes the step of forming a filter having at least one capacitor that has a dielectric layer between the wiring layers at the portions where the adjacent wiring layers are electrically connected to each other or between the top wiring layer and the outer electrodes and at least one inductor that is at least one wiring layer formed in a spiral pattern in the multiple wiring layers. Further, the step of forming the filter includes applying dielectric liquid by an inkjet method to form the dielectric layer and applying conductive liquid in the spiral pattern by the inkjet method to form the inductor. Hashimoto and Black fail to teach or suggest this subject matter.

Claim 15 also calls for forming multiple wiring layers in which stress relief layers and wiring layers are alternately laminated and adjacent wiring layers are electrically connected to each other. In the step of forming the multiple wiring layers, the wiring layer on one face of the top stress relief layer is formed to be a ground plane such that lines having a microstrip line structure are formed in the wiring layer on the other face of the top stress relief layer. Further, the step of forming the multiple wiring layers includes the step of forming a plurality of strip lines that are electromagnetically coupled to each other and are spaced at predetermined intervals by applying conductive liquid by an inkjet method to the lines having the microstrip line structure to form a bandpass filter. Hashimoto and Black fail to teach or suggest this subject matter.

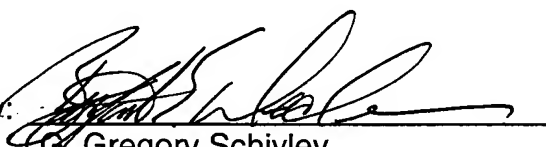
In view of the foregoing, it can be appreciated that Hashimoto and Black fail to teach or suggest the subject matter of independent claims 1, 7, 14 and 15. Hashimoto and Black therefore also fail to teach or suggest the subject matter of dependent claims 2-6, 8-13 and 16. Accordingly, reconsideration and withdrawal of these rejections are respectfully requested.

### CONCLUSION

It is believed that all of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider and withdraw all presently outstanding rejections. It is believed that a full and complete response has been made to the outstanding Office Action, and as such, the present application is in condition for allowance. Thus, prompt and favorable consideration of this amendment is respectfully requested. If the Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

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